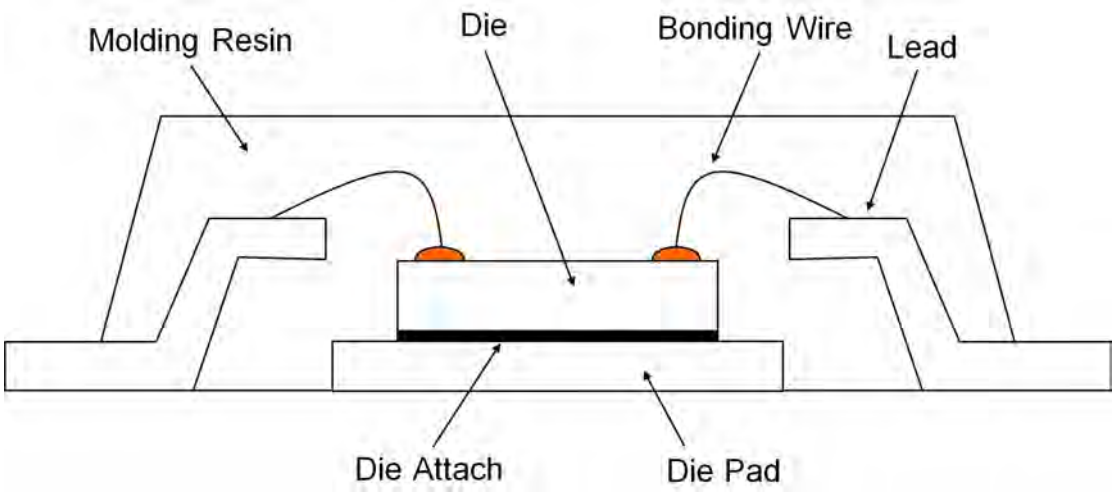
Package Information : HVSOF6

1. Package Information

Package Name	HVSOF6
Type	SOP
Pin Count	6
Package Weight [g]	0.0077
Lead Finish	Pure Tin
MSL	Level1

2. Package Structure



3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

Packing Form		Tape&Reel
Packing Quantity	[pcs]	3,000
PIN 1 Orientation		TR

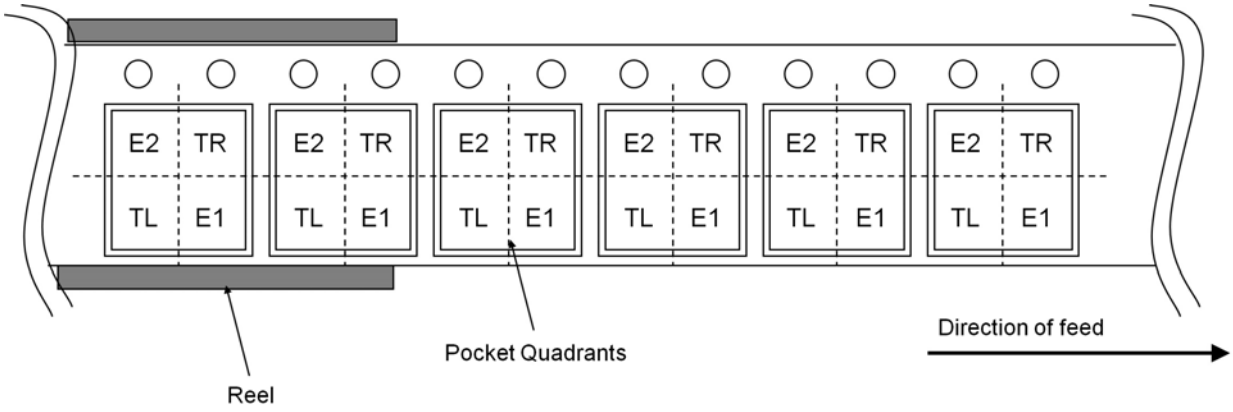


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

E2 : PIN1 is placed to the top left corner. TR : PIN1 is placed to the top right corner.

TL : PIN1 is placed to the lower left. E1 : PIN1 is placed to the lower right.

Fig.1 PIN 1 Orientation in Tape

3.2 Use material

Item	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Unit box	Cardboard
Shipping box	Cardboard

3.3 Leader specification

No component pockets are 160 mm or more.

3.4 Trailer specification

No component pockets are 40 mm or more. Tape is free from reel.

3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

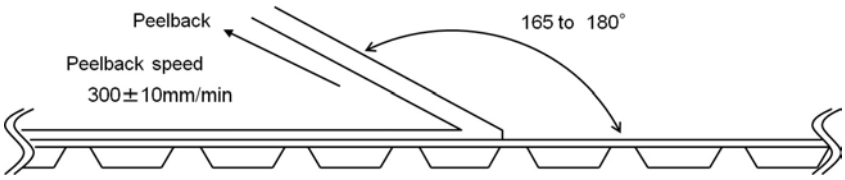


Fig. 2 Test method

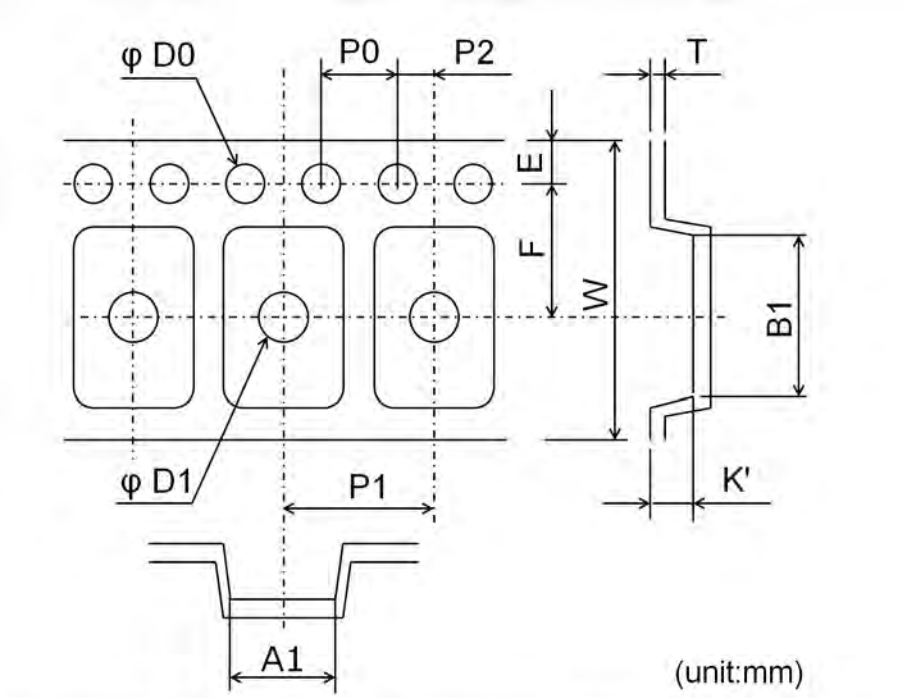
3.6 Missing Ics

(1) No consecutive dropouts.

(2) A maximun 0.1 % of specified number of products in each packing may be missing.

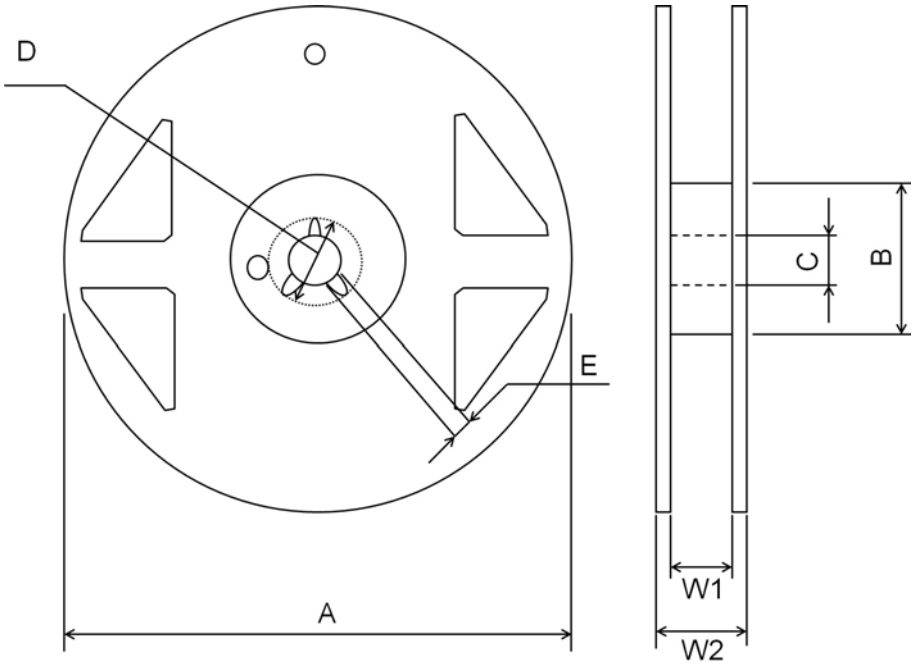
3.7 Tape and Reel Specification

3.7.1 Tape Dimension



	Tape Dimension	Tape Tolerance
A1	2.00	±0.1
B1	3.40	±0.1
D0	φ1.5	+0.1/-0
D1	φ0.8	±0.1
E	1.75	±0.1
F	3.50	±0.05
K'	0.85	±0.1
P0	4.00	±0.1
P1	4.00	±0.1
P2	2.00	±0.1
T	0.30	±0.05
W	8.00	±0.3

3.7.2 Reel Dimension



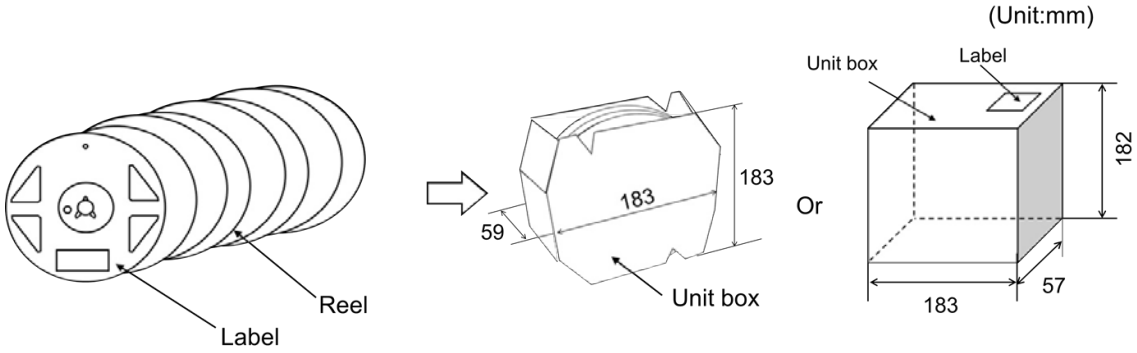
(unit:mm)

	Reel Dimension	Reel Tolerance
A	180	+0/-1.5
B	60	+1.0/-0
C	13	±0.2
D	21	±0.8
E	2	±0.5
W1	9	+1.0/-0
W2	11.4	±1.0

3.8 Packing Method

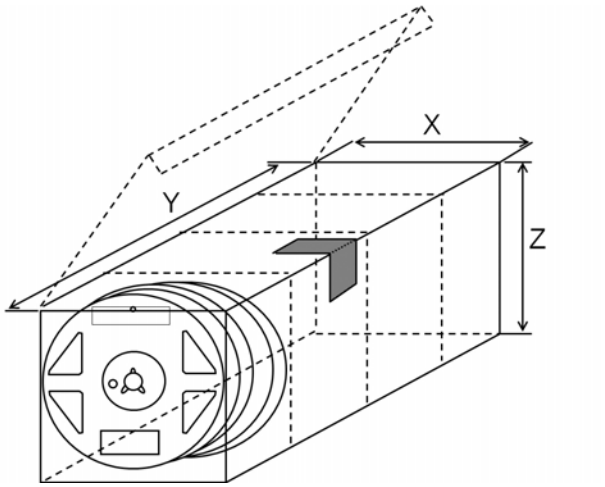
3 reel(s) or less per unit box

(Unit:mm)



3.9 Packing Style

4 unit boxes or less per shipping box



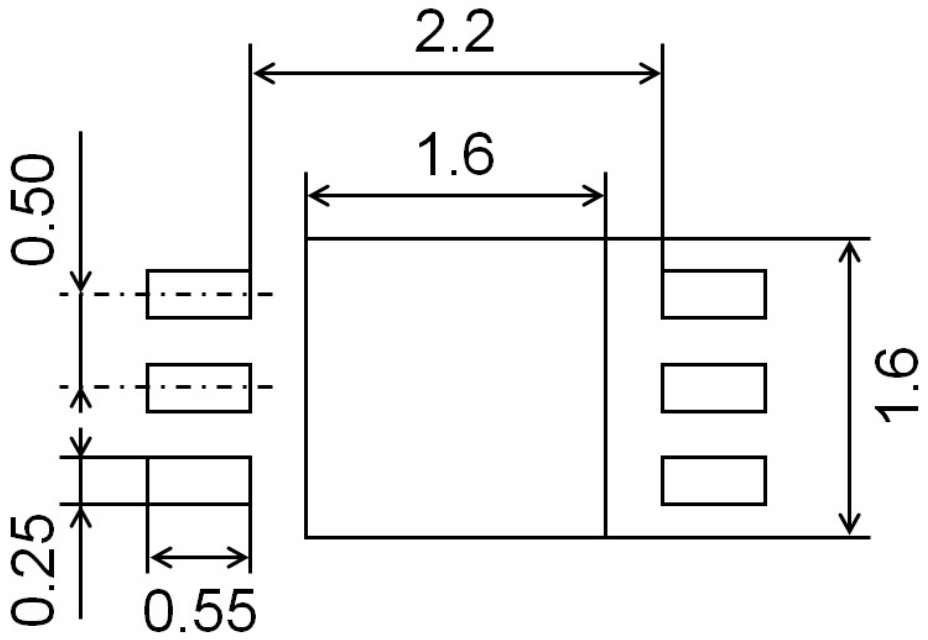
(unit:mm)

Shipping Box Dimension	
X	190
Y	255
Z	193

3.10 Label Specification

Label Example

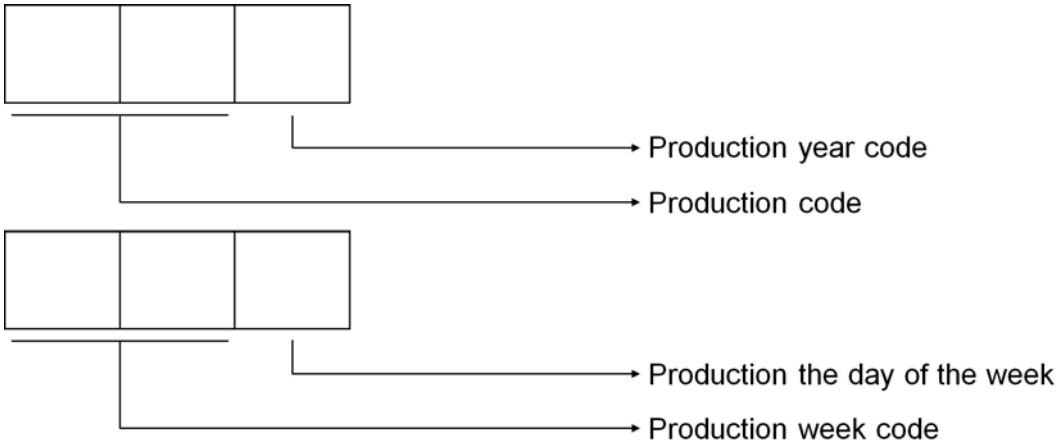
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification



6. Storage conditions

6.1 Storage environment

Recommended storage conditions

	Min.	Max.	Unit
Temperature	5	30	°C
Humidity	-	85	% RH

6.2 Storage period (Start to count since delivery date)

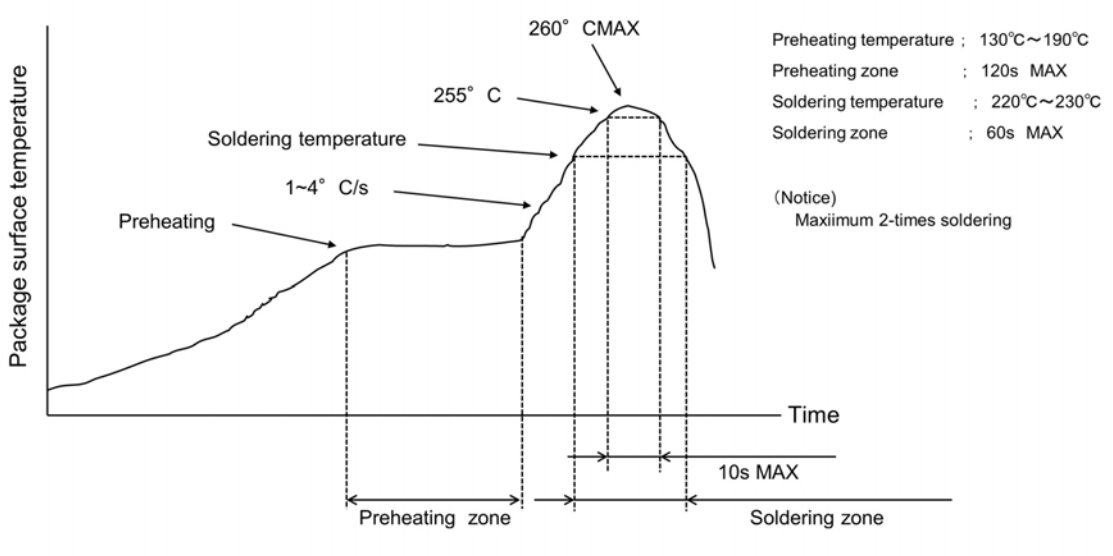
	Min.	Max.	Unit
Storage period	-	1	year

6.3 Drying process

Dryprocess is not required before solder mounting.

7. Soldering conditions

7.1 Recommended temperature profile for reflow

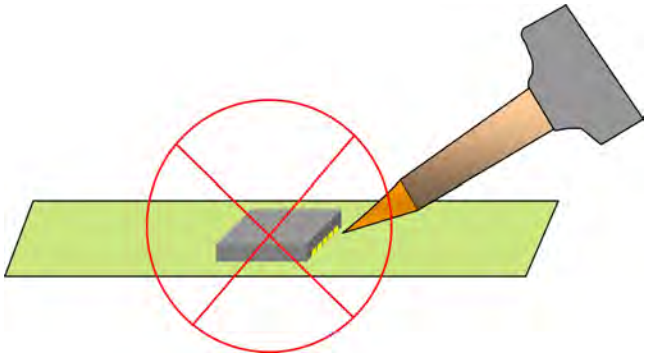


7.2 For wave soldering

The wave soldering method is not supported.

7.3 For solder iron

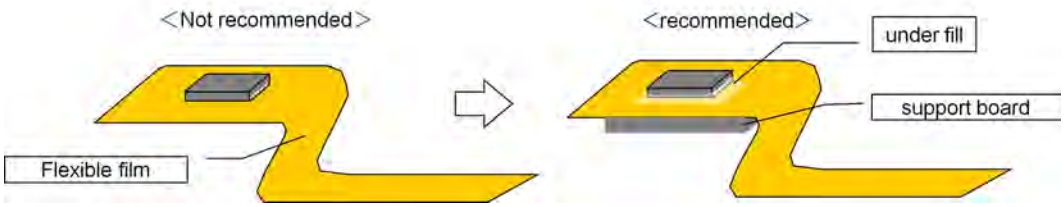
Rework by soldering iron is not allowed or it may cause mold crack and terminal open.



7.4 Caution for solder mounting

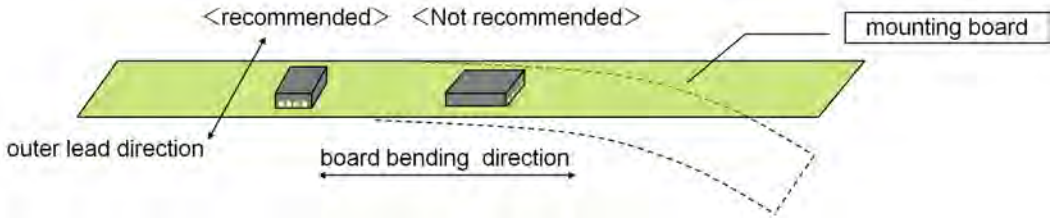
7.4.1 For mounting on flexible film

Mounting on flexible film, film bend may occur lack of lead from package, usage of support board and under fill is recommended.



7.4.2 For Mounting long and narrow board

Mounting on long and narrow board, bending stress may occur a luck of lead from package, bending board direction and outer lead direction is recommended as drawing (vertically layout) and under fill usage is recommended.



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